

Product Summary

BV_{DSS} (@ T_J Max)	$R_{DS(ON)}$ Max	I_D $T_C = +25^\circ C$
650V	2.5Ω @ $V_{GS} = 10V$	3.0A

Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

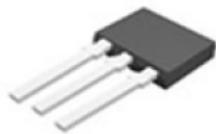
Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

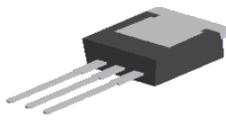
Mechanical Data

- Case: TO251 and TO251 (Type TH)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.33 grams (Approximate)

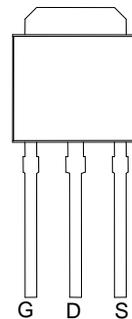
TO251 and TO251 (Type TH)



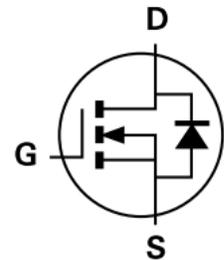
Top View



Bottom View



Top View
Pin Configuration



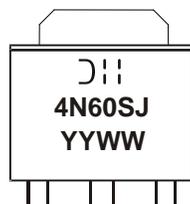
Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMG4N60SJ3	TO251	75 pieces / Tube
DMG4N60SJ3	TO251 (Type TH)	75 pieces / Tube

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



Manufacturer's Marking
 4N60SJ = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Last Two Digits of Year (ex: 16 = 2016)
 WW or WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V _{DSS}	600	V
Gate-Source Voltage	V _{GSS}	±30	V
Continuous Drain Current (Note 5) V _{GS} = 10V	I _D	T _C = +25°C	3.0
		T _C = +100°C	1.9
Maximum Body Diode Forward Current (Note 5)	I _S	6.0	A
Pulsed Drain Current (10µs pulse, Duty Cycle = 1%)	I _{DM}	6.0	A
Avalanche Current, L = 60mH (Note 7)	I _{AS}	1.7	A
Avalanche Energy, L = 60mH (Note 7)	E _{AS}	90	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P _D	T _C = +25°C	41
		T _C = +100°C	16
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	47	°C/W
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	3.0	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	600	—	—	V	V _{GS} = 0V, I _D = 250µA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	µA	V _{DS} = 600V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	100	nA	V _{GS} = ±30V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	2.5	—	4.5	V	V _{DS} = V _{GS} , I _D = 250µA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	2.0	2.5	Ω	V _{GS} = 10V, I _D = 2A
Diode Forward Voltage	V _{SD}	—	—	1.4	V	V _{GS} = 0V, I _S = 1A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}	—	532	—	pF	V _{DS} = 25V, f = 1.0MHz, V _{GS} = 0
Output Capacitance	C _{oss}	—	47	—		
Reverse Transfer Capacitance	C _{rss}	—	4	—		
Gate Resistance	R _G	—	3.3	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge (V _{GS} = 10V)	Q _g	—	14.3	—	nC	V _{DD} = 480V, I _D = 4A, V _{GS} = 10V
Gate-Source Charge	Q _{gs}	—	3.3	—		
Gate-Drain Charge	Q _{gd}	—	6.9	—		
Turn-On Delay Time	t _{D(ON)}	—	14	—	ns	V _{DD} = 300V, R _G = 25Ω, I _D = 4A, V _{GS} = 10V
Turn-On Rise Time	t _R	—	34	—		
Turn-Off Delay Time	t _{D(OFF)}	—	32	—		
Turn-Off Fall Time	t _F	—	25	—		
Body Diode Reverse Recovery Time	t _{RR}	—	229	—	ns	di/dt = 100A/µs, V _{DS} = 100V,
Body Diode Reverse Recovery Charge	Q _{RR}	—	1564	—	nC	I _F = 4A

- Notes:
- Device mounted on infinite heatsink.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.
 - Guaranteed by design. Not subject to production testing.
 - Short duration pulse test used to minimize self-heating effect.

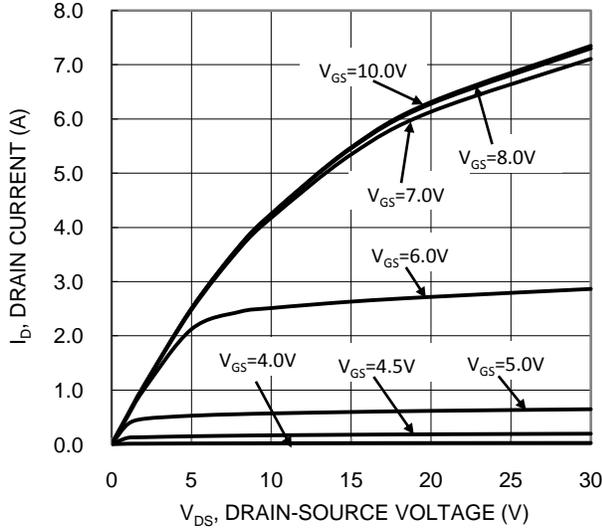


Figure 1. Typical Output Characteristic

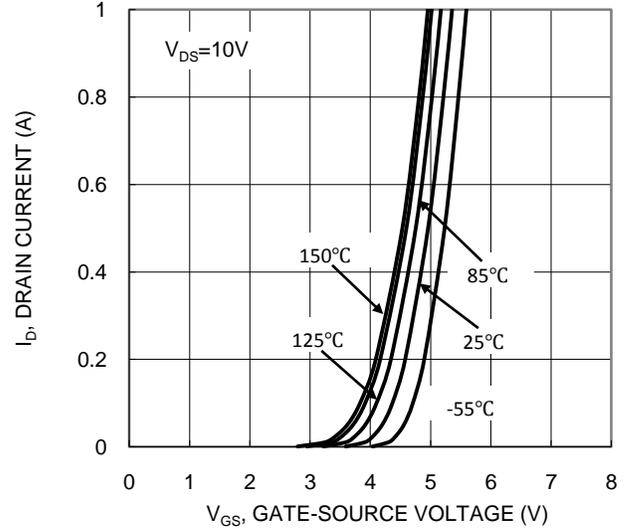


Figure 2. Typical Transfer Characteristic

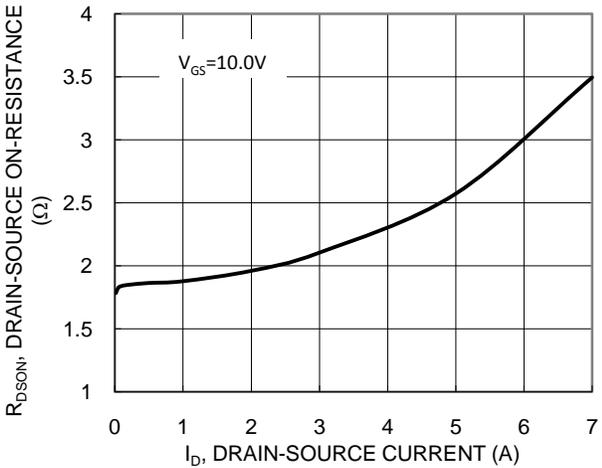


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

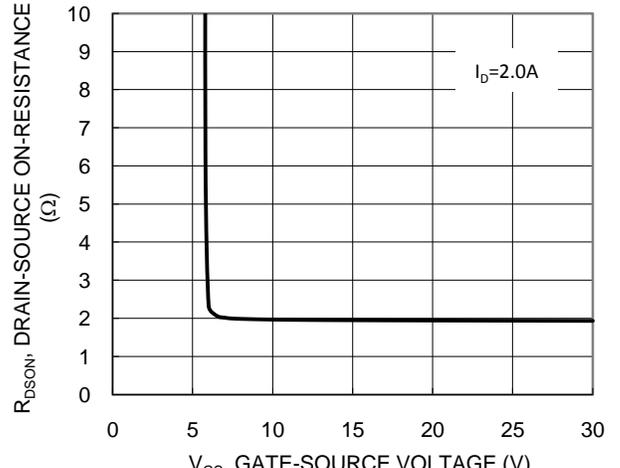


Figure 4. Typical Transfer Characteristic

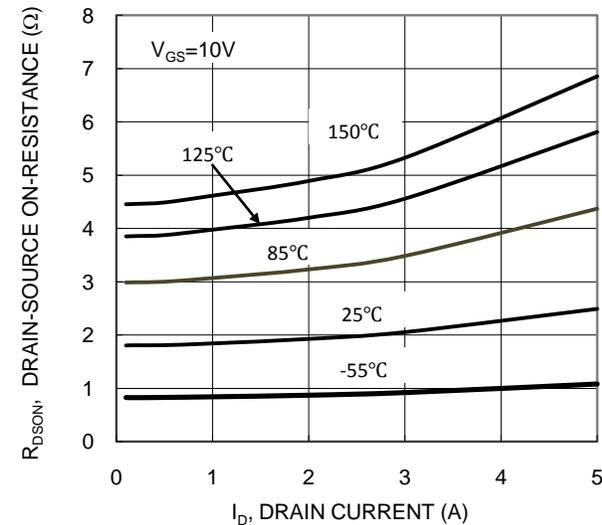


Figure 5. Typical On-Resistance vs Drain Current and Temperature

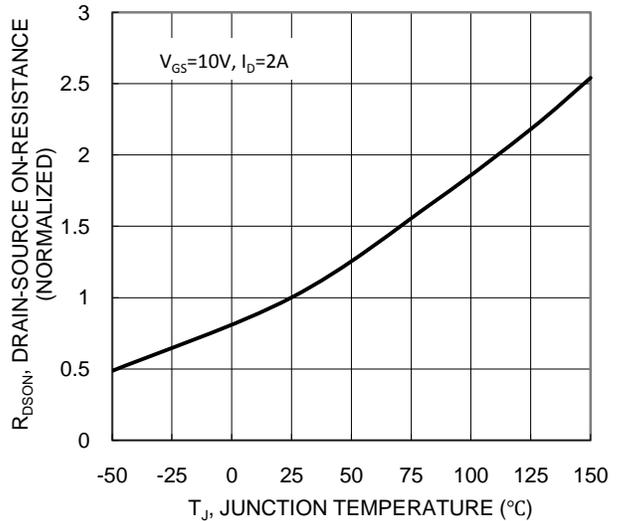


Figure 6. On-Resistance Variation with Temperature

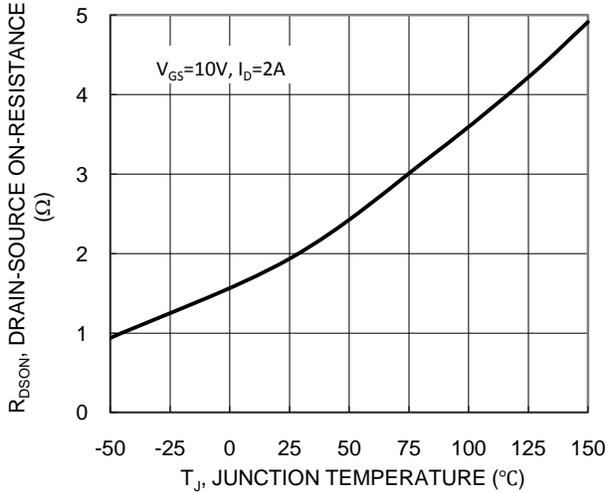


Figure 7. On-Resistance Variation with Temperature

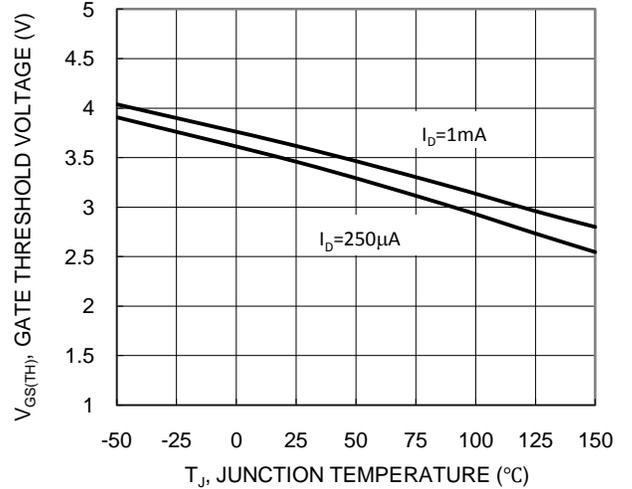


Figure 8. Gate Threshold Variation vs. Junction Temperature

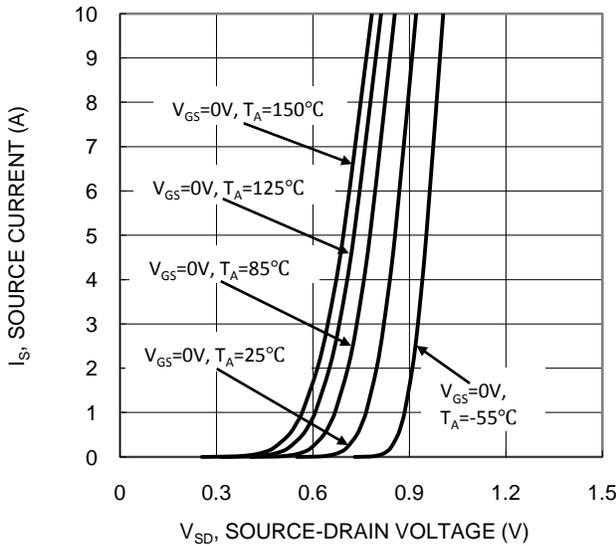


Figure 9. Diode Forward Voltage vs. Current

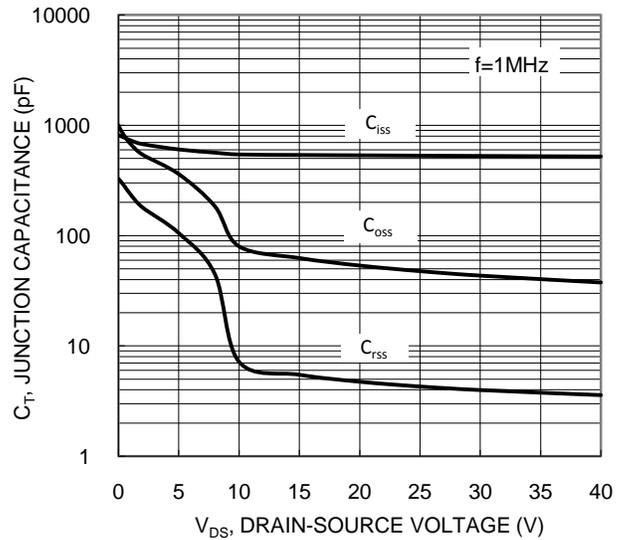


Figure 10. Typical Junction Capacitance

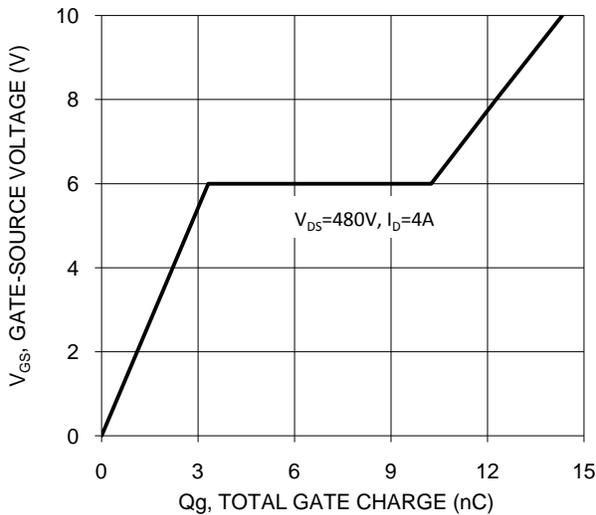


Figure 11. Gate Charge

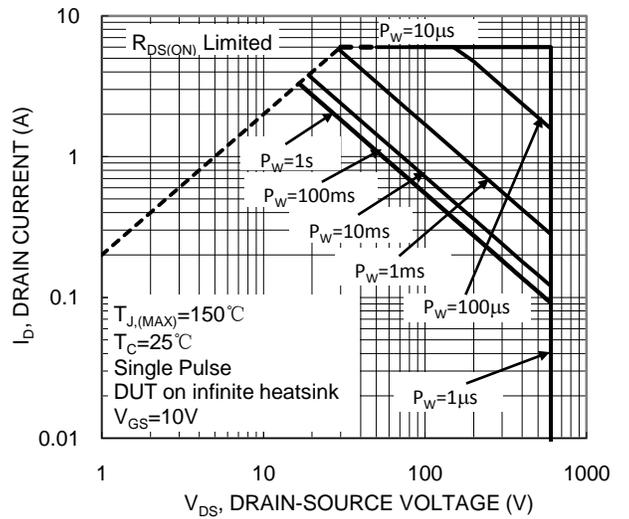
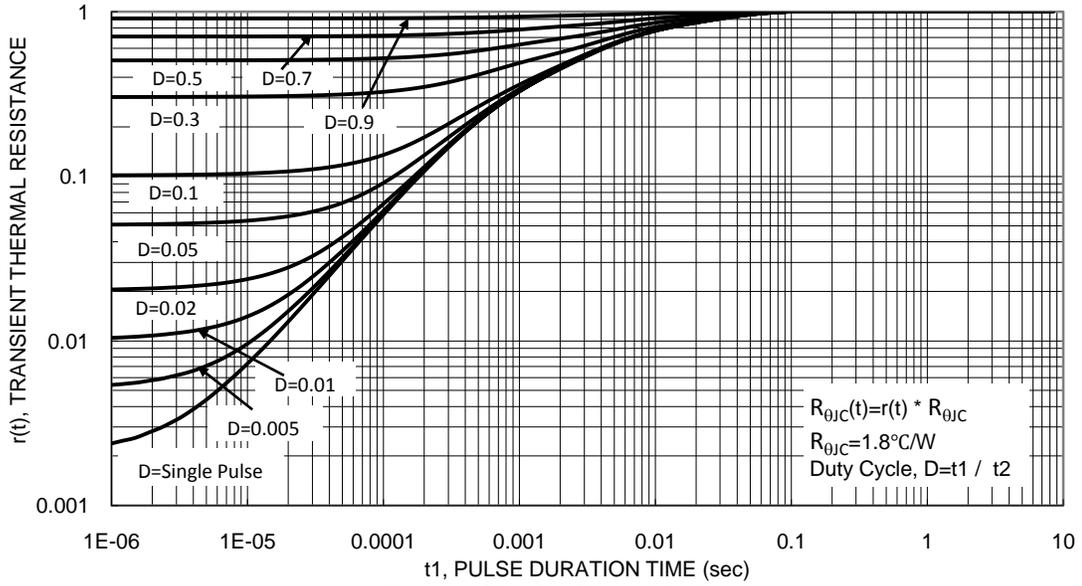


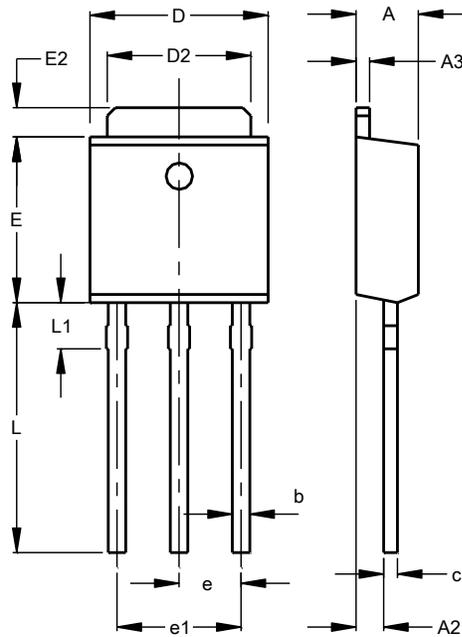
Figure 12. SOA, Safe Operation Area



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: TO251

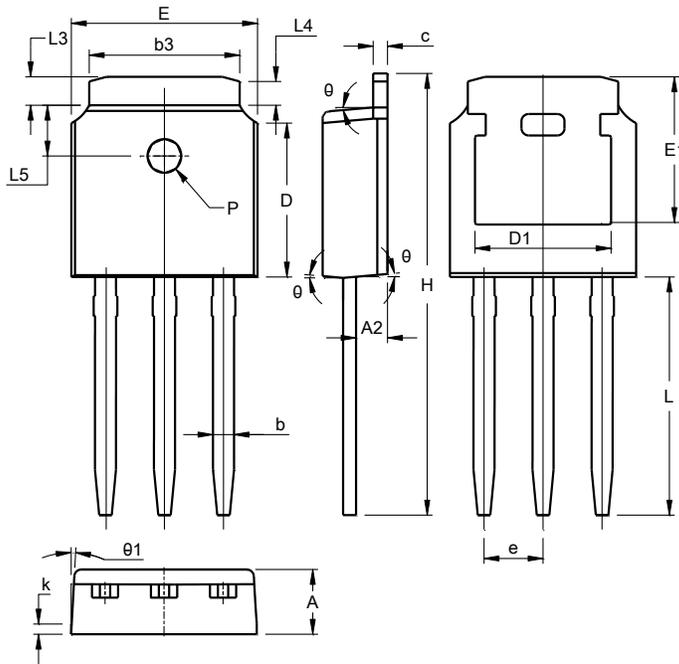


TO251		
Dim	Min	Max
A	2.20	2.40
A2	0.95	1.15
A3	0.45	0.55
b	0.50	0.70
c	0.45	0.55
D	6.45	6.75
D2	5.20	5.40
E	5.95	6.25
E2	0.95	1.25
e	2.24	2.34
e1	4.43	4.73
L	9.00	9.40
L1	1.30	1.70
All Dimensions in mm		

Package Outline Dimensions (Cont.)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(2) Package Type: TO251 (Type TH)



TO251 (Type TH)			
Dim	Min	Max	Typ
A	2.20	2.40	2.30
A2	0.97	1.17	1.07
b	0.68	0.90	0.78
b3	5.20	5.50	5.33
c	0.43	0.63	0.53
D	5.98	6.22	6.10
D1	5.30 REF		
e	2.286 BSC		
E	6.40	6.80	6.60
E1	4.63	5.03	4.83
H	16.22	16.82	16.52
k	0.40 REF		
L	9.15	9.65	9.40
L3	0.88	1.28	1.02
L4	0.75 REF		
L5	1.65	1.95	1.80
theta	5°	9°	7°
theta1	5°	9°	7°
All Dimensions in mm			

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